

Abstract

The present invention provides a semiconductor substrate cleaning method including a step of removing an adhesive layer provided on a semiconductor substrate by use of a remover composition, wherein the remover composition contains a solvent but no salt; and the solvent includes an organic solvent represented by formula (L) (wherein each of L¹ and L² represents a C2 to C4 alkyl group, and L³ represents O or S) in an amount of 80 mass% or more.



[No figure]